

SPONSORSHIP FORM for SMACD2024

SMACD 2024 – International Conference on Synthesis, Modeling, Analysis and Simulation Methods and Applications to Circuit Design 2-5 July, Volos, Greece

The 2024 edition of the International Conference on Synthesis, Modeling, Analysis and Simulation Methods and Applications to Circuit Design (SMACD) will be held in Volos, Greece. SMACD is a forum devoted to modeling, simulation, and synthesis for Analog, Mixed-signal, RF (AMS/RF), and multi-domain (nanoelectronics, biological, MEMS, optoelectronics, etc.) integrated circuits and systems, as well as, emerging technologies and applications. Opensource tools and methods for IC design and experiences with modeling, simulation, and synthesis techniques in diverse application areas are also welcomed. Objective technologies include CMOS, beyond CMOS, and More-than-Moore such as MEMs, power devices, sensors, passives, etc. SMACD is technically co-sponsored by the IEEE, IEEE CEDA and IEEE CASS, and its proceedings will be published in IEEE Xplore.

The SMACD 2024 organization makes available **4 sponsor packages**, respectively, **Diamond** (exclusive to 3 sponsors), **Platinum**, **Gold** and **Silver**. The 4 sponsor packages include different company involvement in the conference program & events, as well as company exhibition & accommodation (please check the table below).

	SILVER	GOLD	PLATINUM	DIAMOND
Logo on Conference Website & Final Program	V	V	V	V
Acknowledgment Slide during Opening/Closing & Session Breaks	V	√	V	V
Promotional Material in Attendee Kit	V	√	V	✓
Logo on Banner at Conference Venue		V	V	V
Full-Page Ad in Final Program		V	V	✓
Featured in Best Paper Award		✓	V	V
Featured in Student Competition (EDA & IC Design) Awards			V	V
Featured Sponsor of Welcome Reception			V	V
Featured Sponsor of Gala Dinner				V
Featured Sponsor of the SMACD Job Fair & Luncheon*				V
Email Distributions to the Conference Attendee List		1	2	3
Full-Access Conference Registrations		2	3	4
Exhibition Booth at the Conference Fair		V	V	V
Presentation (10') at the Industrial Session		V	V	V
Participation at the SMACD Job Fair & Luncheon*		V	V	V
Tutorial Proposal (90')			V	V
Keynote Lecture Proposal (60')				V
Accommodations (4 days) at the 5★ Domotel Xenia Volos Hotel			1	2
(https://domotel.gr/xenia-volos/)			1	
	1,500€	4,000€	7,000€	10,000€

^{*} The Job Fair will take place after the Industrial presentations, where eligible students and graduates can connect with industry representatives and learn about job openings or attend on-site interviews. Attendees of the Job Fair will be encouraged to submit their CVs in advance for circulation, while industry participants will be able to publicize their job openings on the conference website. Please, reach out if you are interested in the Job Fair and want to know more.



List of Past SMACD Patrons

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Your sponsoring efforts make a significant contribution to keeping the conference fees at an acceptable level. To ensure the timely establishment of the fee structure prior to the commencement of registration, we would greatly appreciate your confirmation of your sponsorship contribution by February 1, 2024.

Please complete the following form for submission:

Sponsorship Packages:	Diamond	Platinum	Gold	Silver
Sponsorship Fee (including taxes):	10000€	7000€	4000€	1500€
Sponsorship Package Selection:				

Company: VAT ID:	With your signature, you grant us the free and non-exclusive right to use your logos, images and text materials provided by you for all publications within the scope of your sponsoring package for the SMACD2024 conference.
Contact Person:	Please send this form filled and signed to: Eftychia Saiti
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